FIG. 1

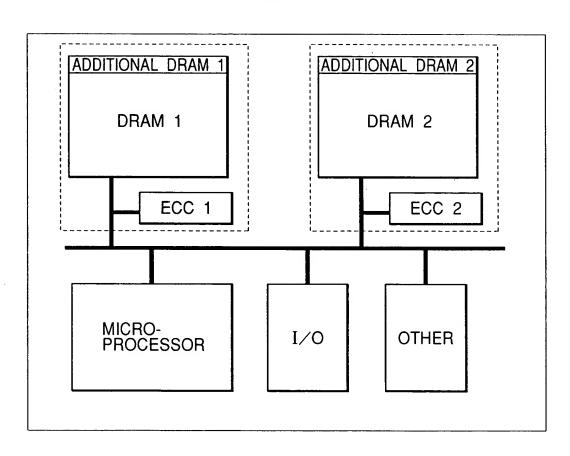


FIG. 2

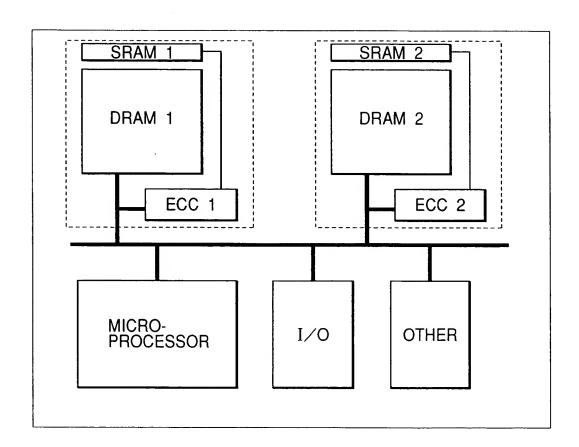


FIG. 3

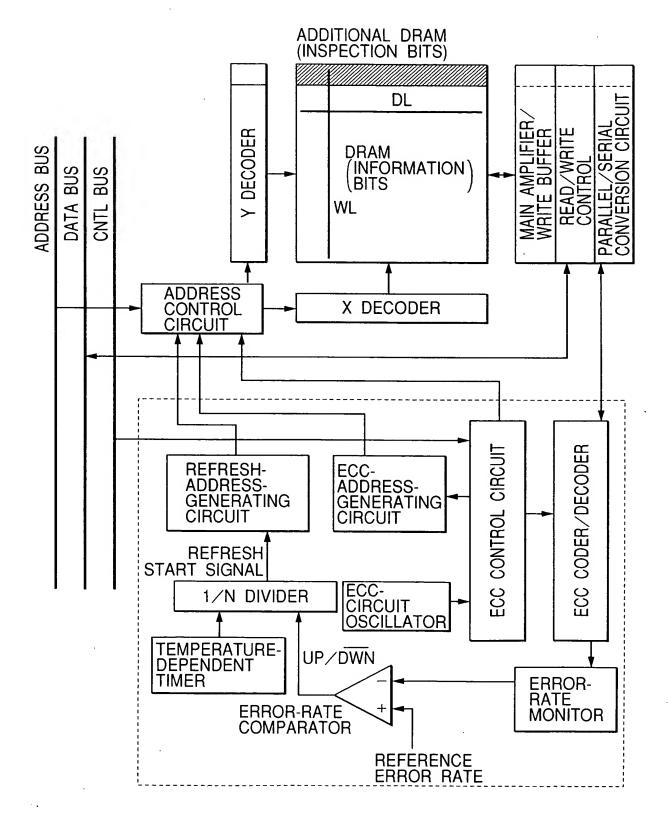


FIG. 4

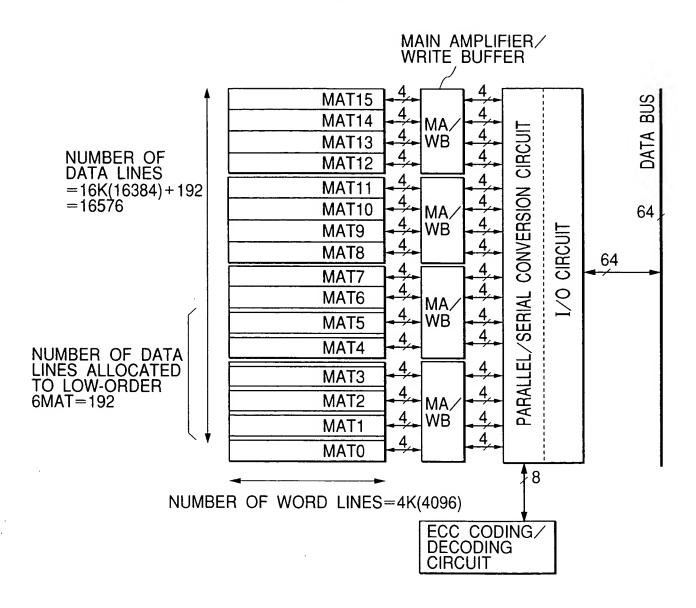


FIG. 5

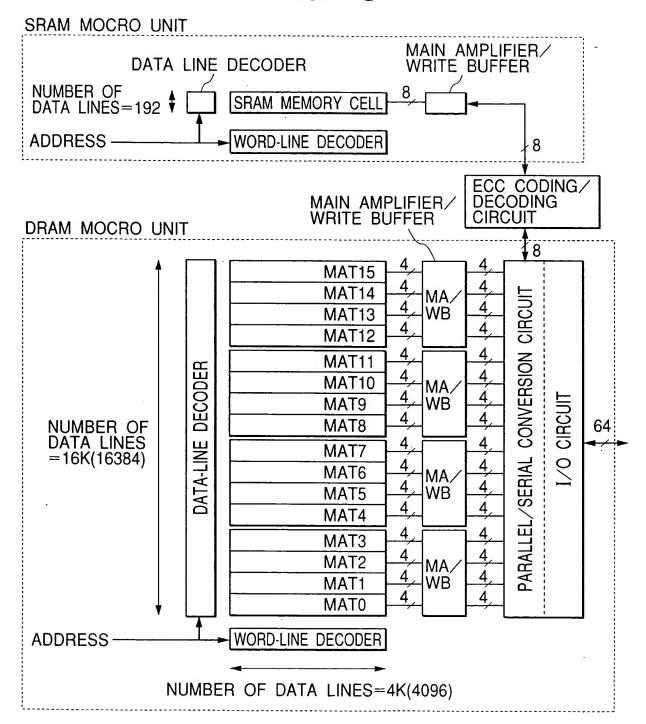


FIG. 6

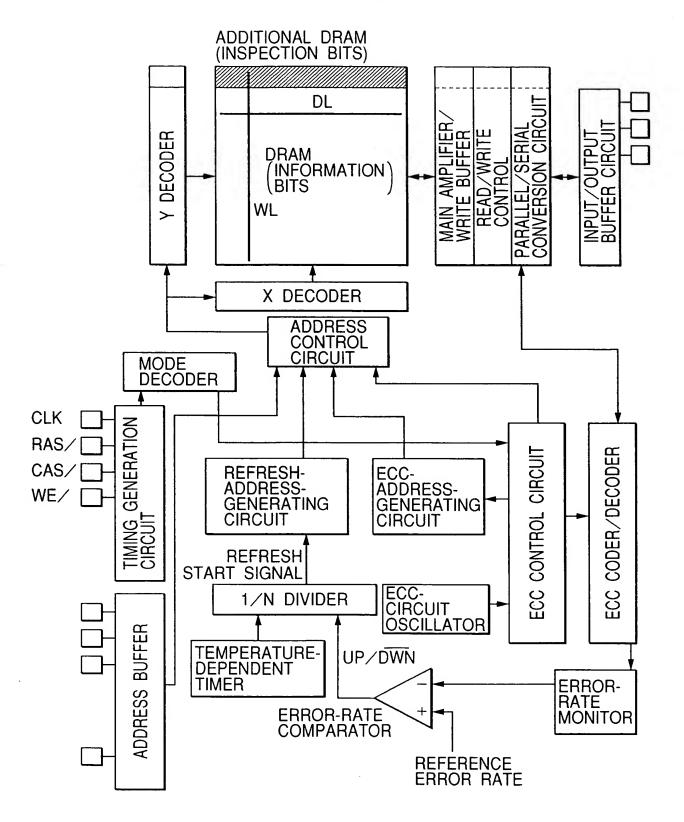


FIG. 7

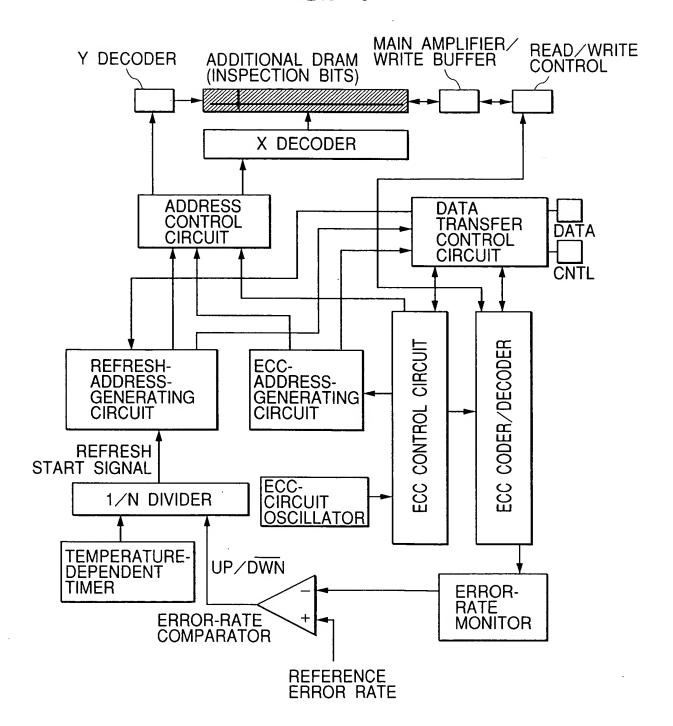


FIG. 8

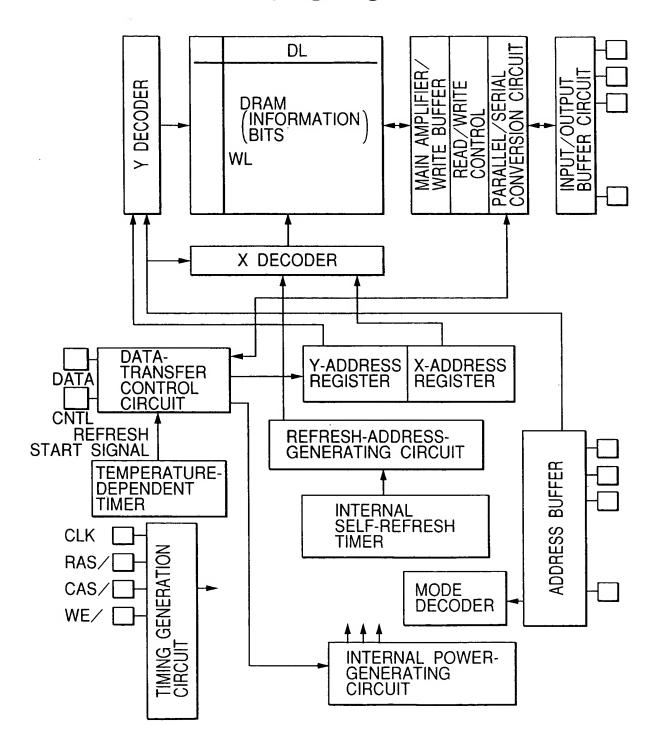


FIG. 9

EXTERNAL ECC (INSPECTION BITS) UNIT MAIN AMPLIFIER/ WRITE BUFFER DATA-LINE DECODER NUMBER OF DATA LINES=192 SRAM MEMORY CELLS WORD-LINE DECODER ADDRESS -ECC CODING/ DECODING CIRCUIT DATA -ECC TOTAL DATA TRANSFER CONTROL CIRCUIT CONTROL CNTL MAIN-BODY DRAM (INFORMATION BIT) UNIT DATA DATA TRANSFER MAIN AMPLIFIER/ WRITE BUFFER CONTROL 18 MAT15 DQ₀ MAT14 MA/ DQ₁ MAT13 **WB** PARALLEL/SERIAL CONVERSION CIRCUIT MAT12 DQ2 CIRCUIT MAT11 DQ3 DECODER MAT10 MA/ BUFFER (MAT9 **WB** I/O CIRCUIT NUMBER OF MAT8 DATA LINES DATA-LINE 32 MAT7 NPUT/OUTPUT =16K(16384)MAT6 MA/ MAT5 **WB** MAT4 MAT3 MAT2 MA/ MAT1 WB **DQ31** MAT0 WORD-LINE DECODER ADDRESS NUMBER OF DATA LINES=4K(4096)

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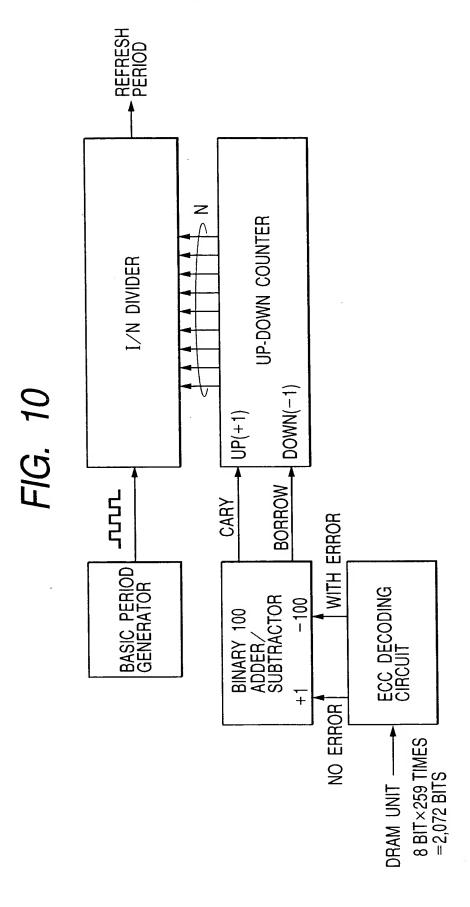
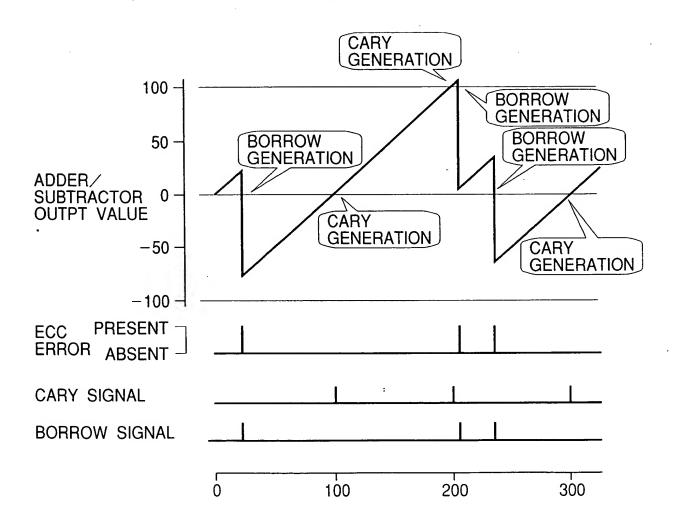
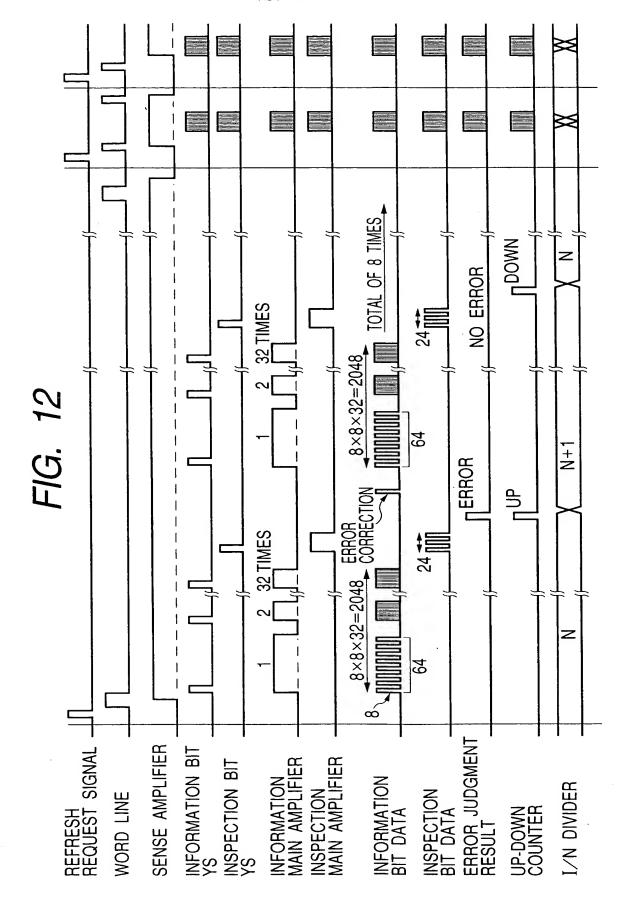
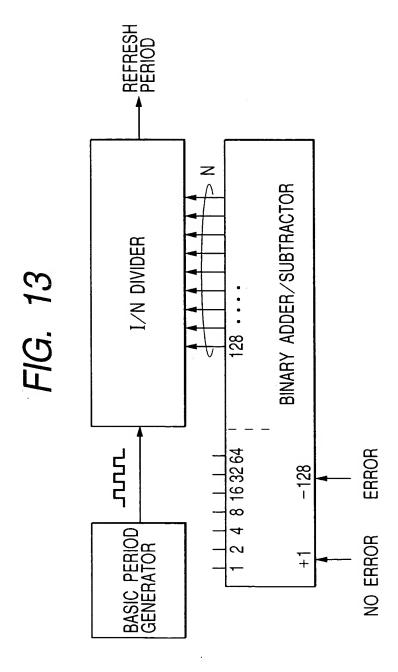


FIG. 11







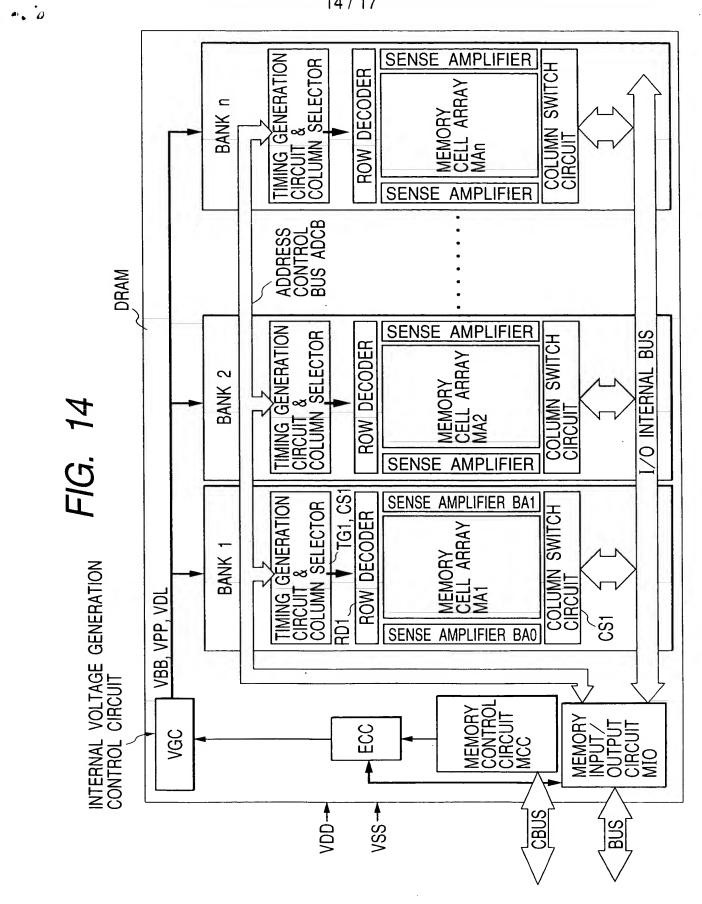


FIG. 15

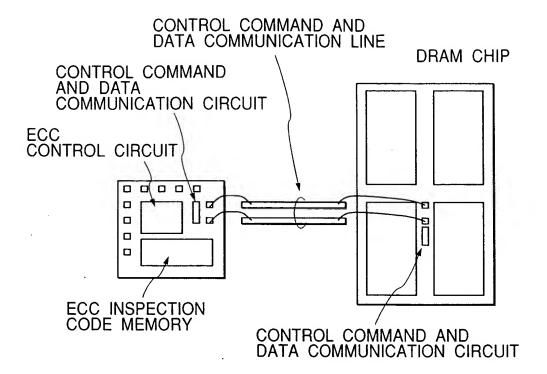


FIG. 16(A)

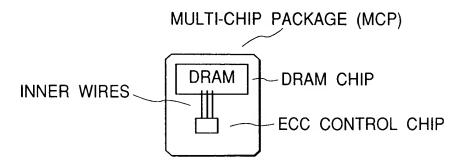


FIG. 16(B)

CHIP-SIDE PACKAGE (CSP)

ECC CONTROL CHIP

DRAM CHIP

FIG. 17

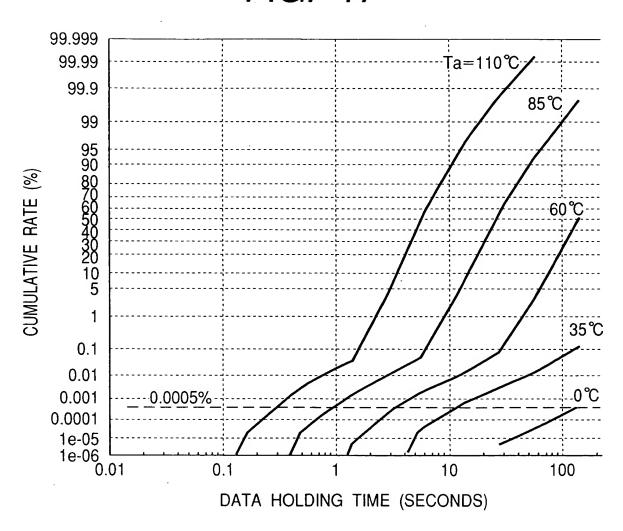


FIG. 18

